LM79LXXAC Series 3-Terminal Negative Regulators

Check for Samples: LM79L05, LM79L12, LM79L12AC, LM79L15, LM79L15AC

FEATURES

- **Preset Output Voltage Error is Less than ±5% Over Load, Line and Temperature**
- **Specified at an Output Current of 100mA**
- **Easily Compensated with a Small 0.1µF Output Capacitor**
- **Internal Short-Circuit, Thermal and Safe Operating Area Protection**
- **Easily Adjustable to Higher Output Voltages**
- **Maximum Line Regulation Less than 0.07% V_{OUT}/V**
- **Maximum Load Regulation Less than 0.01% V_{OUT}/mA**
- **See AN-1112 (SNVA009) for DSBGA Considerations**

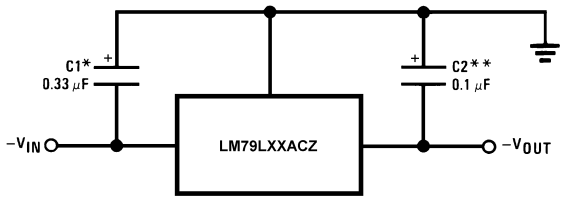
DESCRIPTION

The LM79LXXAC series of 3-terminal negative voltage regulators features fixed output voltages of −5V, −12V, and −15V with output current capabilities in excess of 100mA. These devices were designed using the latest computer techniques for optimizing the packaged IC thermal/electrical performance. The LM79LXXAC series, when combined with a minimum output capacitor of 0.1µF, exhibits an excellent transient response, a maximum line regulation of 0.07% V_O/V, and a maximum load regulation of 0.01% V_O/mA.

The LM79LXXAC series also includes, as self-protection circuitry: safe operating area circuitry for output transistor power dissipation limiting, a temperature independent short circuit current limit for peak output current limiting, and a thermal shutdown circuit to prevent excessive junction temperature. Although designed primarily as fixed voltage regulators, these devices may be combined with simple external circuitry for boosted and/or adjustable voltages and currents. The LM79LXXAC series is available in the 3-lead TO package, the 8-lead SOIC package, and the 6-Bump DSBGA package.

For output voltages other than the pre-set -5V, -12V and -15V, the LM137L series provides an adjustable output voltage range from -1.2V to -47V.

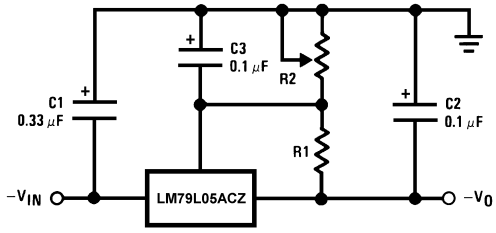
Typical Applications



*Required if the regulator is located far from the power supply filter. A 1µF aluminum electrolytic may be substituted.

**Required for stability. A 1µF aluminum electrolytic may be substituted.

Figure 1. Fixed Output Regulator

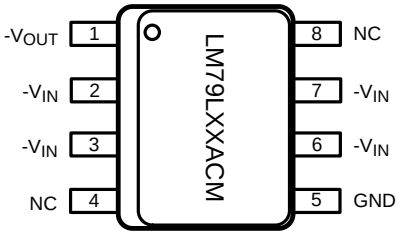


$-V_0 = -5V - (5V/R1 + I_Q) \bullet R2$,
$5V/R1 > 3\ I_Q$

Figure 2. Adjustable Output Regulator

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Connection Diagram



Pins labeled 'NC' on LM79LXXACM 8-Lead SOIC (pin 4 and pin 8) are Open, no internal connection.

Figure 3. 8-Lead SOIC Narrow (D)
Top View

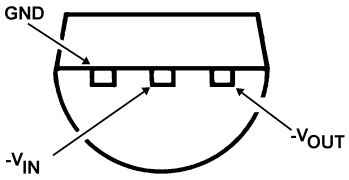


Figure 4. 3–Lead TO-226 (LP)
Bottom View

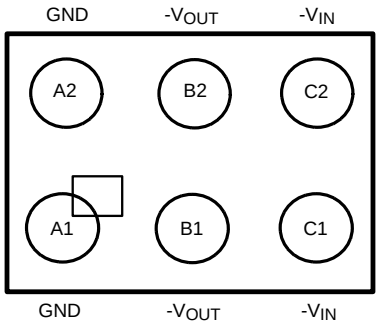


Figure 5. 6-Bump DSBGA
Top View (Bump Side Down)

Absolute Maximum Ratings[1][2]

Input Voltage	
V_O = −5V, −12V, −15V	−35V
Internal Power Dissipation [3]	Internally Limited
Operating Temperature Range	0°C to +70°C
Maximum Junction Temperature	+125°C
Storage Temperature Range	−55°C to +150°C
Lead Temperature	
(Soldering, 10 sec.)	260°C

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional.
(2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
(3) Thermal resistance of TO-226 (LP) package is 60°C/W θ_{JC}, 232°C/W θ_{JA} at still air, and 88°C/W at 400 ft/min of air. The θ_{JA} of the LM78LXX in the 6-Bump DSBGA package is 114°C/W when mounted on a 4-Layer JEDEC test board (JESD 51-7). The θ_{JA} of the LM78LXX in the SOIC-8 (D) package is 180°C/W in still air. The maximum junction temperature shall not exceed 125°C on electrical parameters.

Electrical Characteristics [1]

T_A = 0°C to +70°C unless otherwise noted.

Output Voltage			**−5V**			**−12V**			**−15V**			
Input Voltage (unless otherwise noted)			**−10V**			**−17V**			**−20V**			
Symbol	**Parameter**	**Conditions**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Units**
V_O	Output Voltage	T_J = 25°C, I_O = 100mA	−5.2	−5	−4.8	−12.5	−12	−11.5	−15.6	−15	−14.4	V
		1mA ≤ I_O ≤ 100mA	−5.25		−4.75	−12.6		−11.4	−15.75		−14.25	
		$V_{MIN} \le V_{IN} \le V_{MAX}$	(−20 ≤ V_{IN} ≤ −7.5)			(−27 ≤ V_{IN} ≤ −14.8)			(−30 ≤ V_{IN} ≤ −18)			
		1mA ≤ I_O ≤ 40mA	−5.25		−4.75	−12.6		−11.4	−15.75		−14.25	
		$V_{MIN} \le V_{IN} \le V_{MAX}$	(−20 ≤ V_{IN} ≤ −7)			(−27 ≤ V_{IN} ≤ −14.5)			(−30 ≤ V_{IN} ≤ −17.5)			
ΔV_O	Line Regulation	T_J = 25°C, I_O = 100mA			60			45			45	mV
		$V_{MIN} \le V_{IN} \le V_{MAX}$	(−20 ≤ V_{IN} ≤ −7.3)			(−27 ≤ V_{IN} ≤ −14.6)			(−30 ≤ V_{IN} ≤ −17.7)			V
		T_J = 25°C, I_O = 40mA			60			45			45	mV
		$V_{MIN} \le V_{IN} \le V_{MAX}$	(−20 ≤ V_{IN} ≤ −7)			(−27 ≤ V_{IN} ≤ −14.5)			(−30 ≤ V_{IN} ≤ −17.5)			V
ΔV_O	Load Regulation	T_J = 25°C			50			100			125	mV
		1mA ≤ I_O ≤ 100mA										
ΔV_O	Long Term Stability	I_O = 100mA		20			48			60		mV/khrs
I_Q	Quiescent Current	I_O = 100mA		2	6		2	6		2	6	mA
ΔI_Q	Quiescent Current Change	1mA ≤ I_O ≤ 100mA			0.3			0.3			0.3	
		1mA ≤ I_O ≤ 40mA			0.1			0.1			0.1	mA
		I_O = 100mA			0.25			0.25			0.25	mA
		$V_{MIN} \le V_{IN} \le V_{MAX}$	(−20 ≤ V_{IN} ≤ −7.5)			(−27 ≤ V_{IN} ≤ −14.8)			(−30 ≤ V_{IN} ≤ −18)			V
V_n	Output Noise Voltage	T_J = 25°C, I_O = 100mA f = 10Hz − 10kHz		40			96			120		µV
$\Delta V_{IN}/\Delta V_O$	Ripple Rejection	T_J = 25°C, I_O = 100mA f = 120Hz	50			52			50			dB
	Input Voltage Required to Maintain Line Regulation	T_J = 25°C, I_O = 100mA			−7.3			−14.6			−17.7	V
		I_O = 40mA			−7.0			−14.5			−17.5	V

(1) To ensure constant junction temperature, low duty cycle pulse testing is used.

Typical Performance Characteristics

Maximum Average Power Dissipation (TO-226)

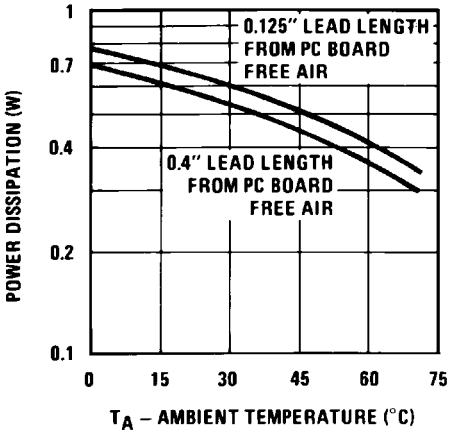


Figure 6.

Peak Output Current

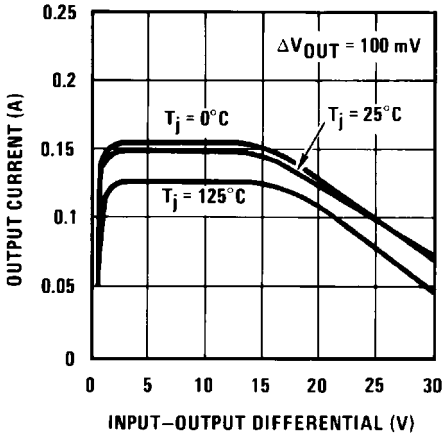


Figure 7.

Short Circuit Output Current

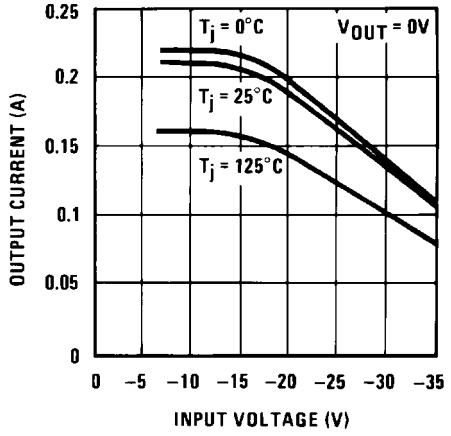


Figure 8.

Dropout Voltage

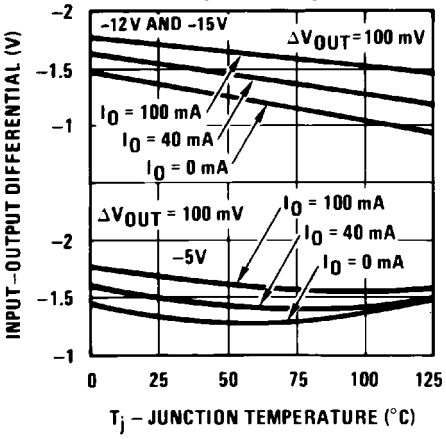


Figure 9.

Ripple Rejection

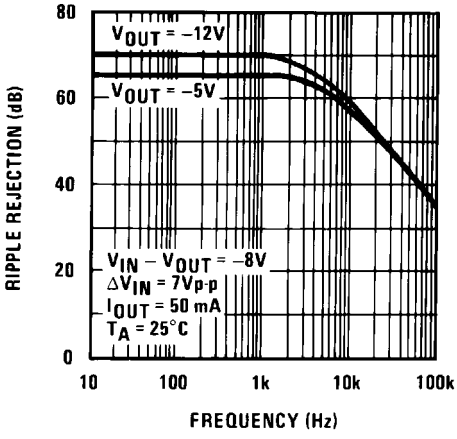


Figure 10.

Output Voltage vs. Temperature (Normalized to 1V @ 25°C)

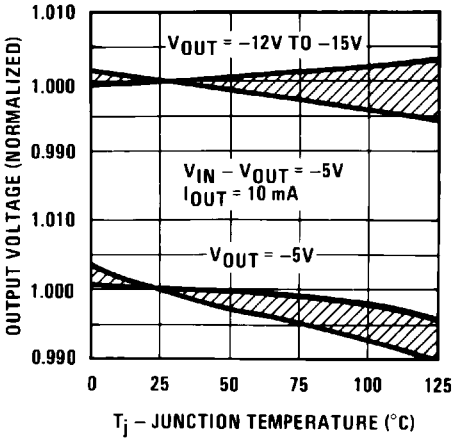


Figure 11.

Typical Performance Characteristics (continued)

Quiescent Current

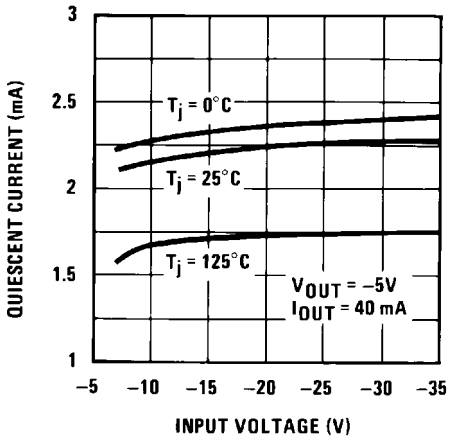


Figure 12.

Output Impedance

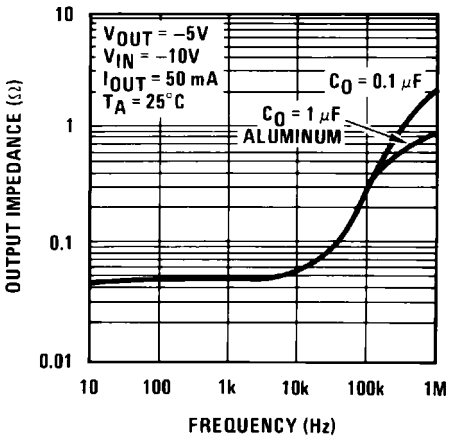


Figure 13.

TYPICAL APPLICATIONS

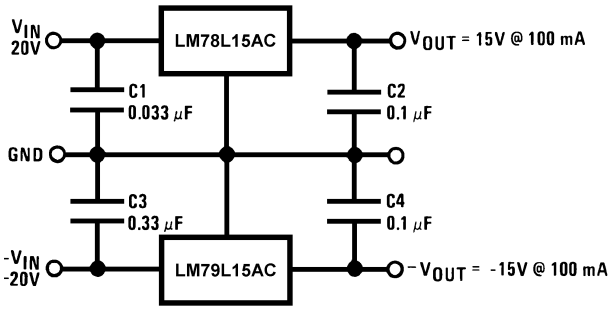


Figure 14. ±15V, 100mA Dual Power Supply

Schematic Diagrams

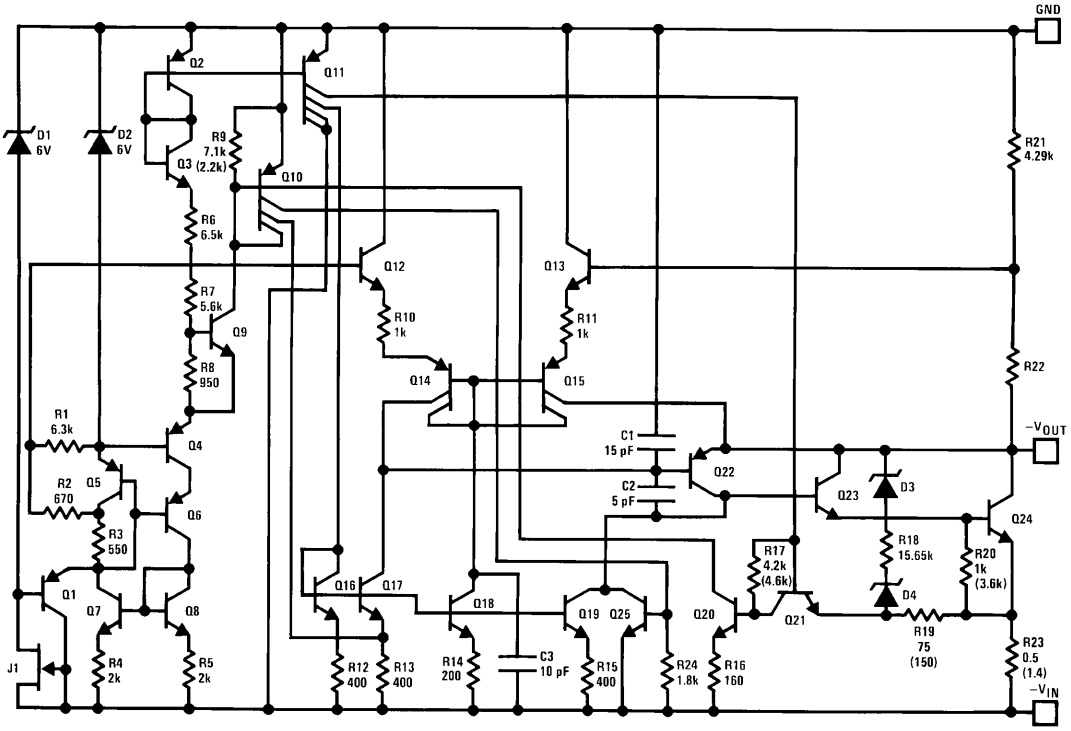


Figure 15. −5V Schematic Diagram

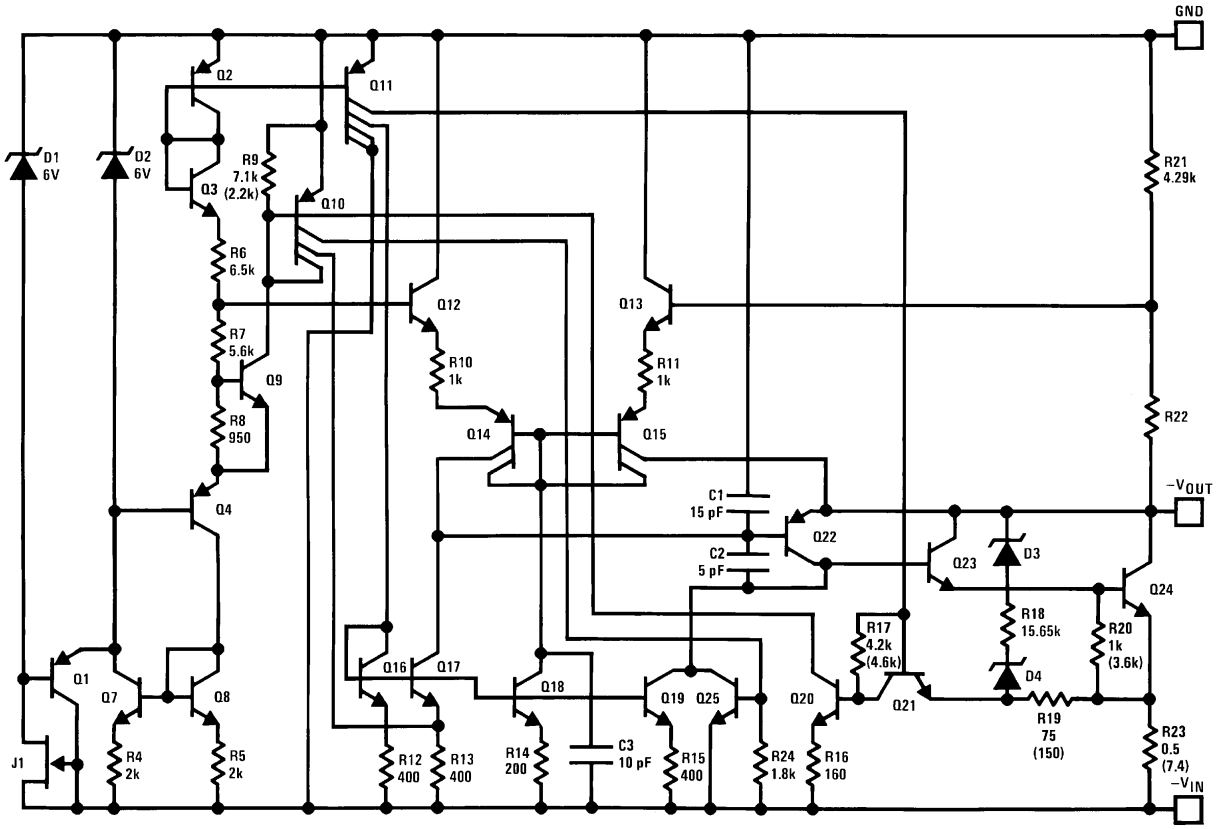


Figure 16. −12V and −15V Schematic Diagram

REVISION HISTORY

Changes from Revision J (April 2013) to Revision K	**Page**
• Changed layout of National Data Sheet to TI format	7

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LM79L05ACM/NOPB	Active	Production	SOIC (D) | 8	95 | TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM79L 05ACM
LM79L05ACM/NOPB.B	Active	Production	SOIC (D) | 8	95 | TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM79L 05ACM
LM79L05ACMX/NOPB	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM79L 05ACM
LM79L05ACMX/NOPB.B	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM79L 05ACM
LM79L05ACTL/NOPB	Active	Production	DSBGA (YZR) | 6	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	0 to 70	P B
LM79L05ACTL/NOPB.B	Active	Production	DSBGA (YZR) | 6	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	0 to 70	P B
LM79L05ACTLX/NOPB	Active	Production	DSBGA (YZR) | 6	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	0 to 70	P B
LM79L05ACTLX/NOPB.B	Active	Production	DSBGA (YZR) | 6	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	0 to 70	P B
LM79L05ACZ/LFT1	Active	Production	TO-92 (LP) | 3	2000 | LARGE T&R	Yes	SN	N/A for Pkg Type	-	320L 79L05
LM79L05ACZ/LFT1.B	Active	Production	TO-92 (LP) | 3	2000 | LARGE T&R	Yes	SN	N/A for Pkg Type	0 to 70	320L 79L05
LM79L05ACZ/NOPB	Active	Production	TO-92 (LP) | 3	1800 | BULK	Yes	SN	N/A for Pkg Type	0 to 70	320L 79L05
LM79L05ACZ/NOPB.B	Active	Production	TO-92 (LP) | 3	1800 | BULK	Yes	SN	N/A for Pkg Type	0 to 70	320L 79L05
LM79L12ACM/NOPB	Active	Production	SOIC (D) | 8	95 | TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM79L 12ACM
LM79L12ACM/NOPB.B	Active	Production	SOIC (D) | 8	95 | TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM79L 12ACM
LM79L12ACMX/NOPB	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM79L 12ACM
LM79L12ACMX/NOPB.B	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM79L 12ACM

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LM79L12ACZ/LFT4	Active	Production	TO-92 (LP) | 3	2000 | LARGE T&R	Yes	SN	N/A for Pkg Type	-	320L 79L12
LM79L12ACZ/LFT4.B	Active	Production	TO-92 (LP) | 3	2000 | LARGE T&R	Yes	SN	N/A for Pkg Type	0 to 70	320L 79L12
LM79L12ACZ/NOPB	Active	Production	TO-92 (LP) | 3	1800 | BULK	Yes	SN	N/A for Pkg Type	0 to 70	320L 79L12
LM79L12ACZ/NOPB.B	Active	Production	TO-92 (LP) | 3	1800 | BULK	Yes	SN	N/A for Pkg Type	0 to 70	320L 79L12
LM79L15ACM/NOPB	Active	Production	SOIC (D) | 8	95 | TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM79L 15ACM
LM79L15ACM/NOPB.B	Active	Production	SOIC (D) | 8	95 | TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM79L 15ACM
LM79L15ACMX/NOPB	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM79L 15ACM
LM79L15ACMX/NOPB.B	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM79L 15ACM

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

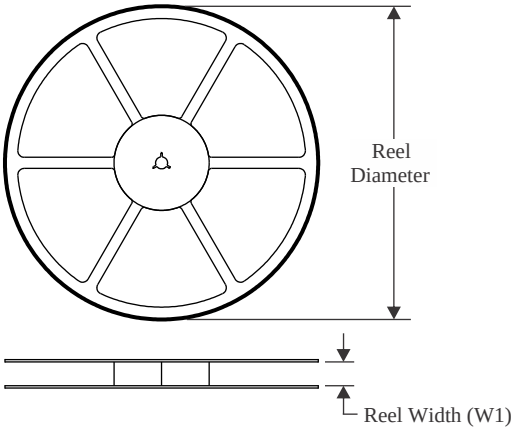
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

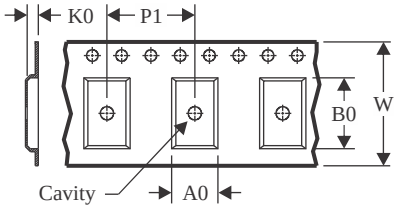
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

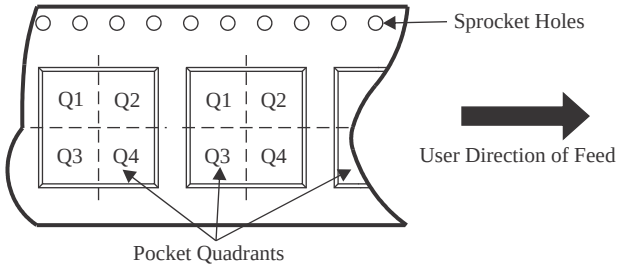


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

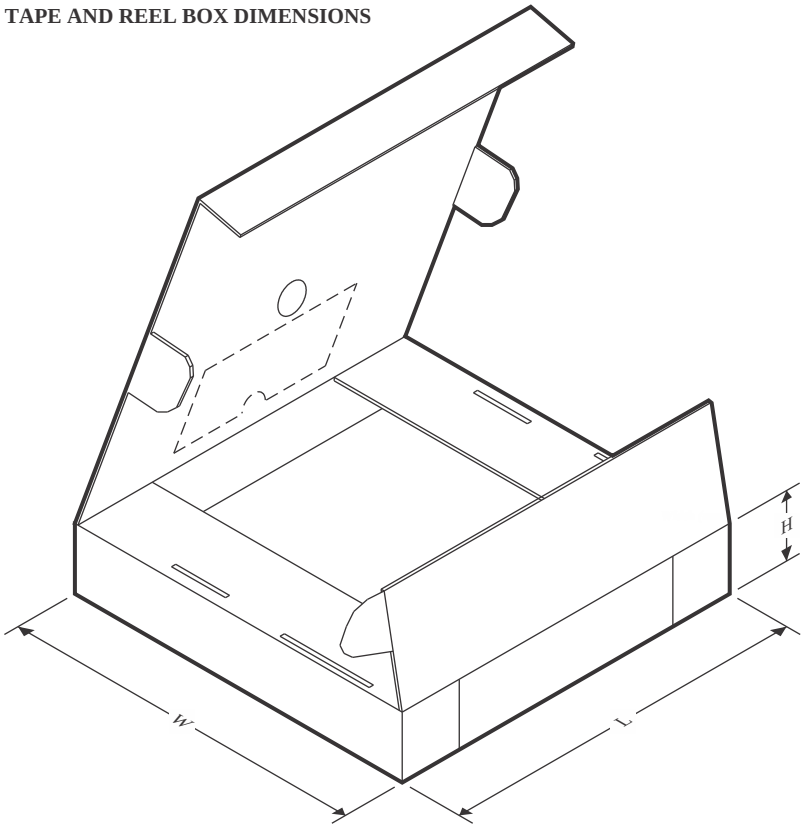
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM79L05ACMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM79L05ACTL/NOPB	DSBGA	YZR	6	250	178.0	8.4	1.09	1.88	0.76	4.0	8.0	Q1
LM79L05ACTLX/NOPB	DSBGA	YZR	6	3000	178.0	8.4	1.09	1.88	0.76	4.0	8.0	Q1
LM79L12ACMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM79L15ACMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1

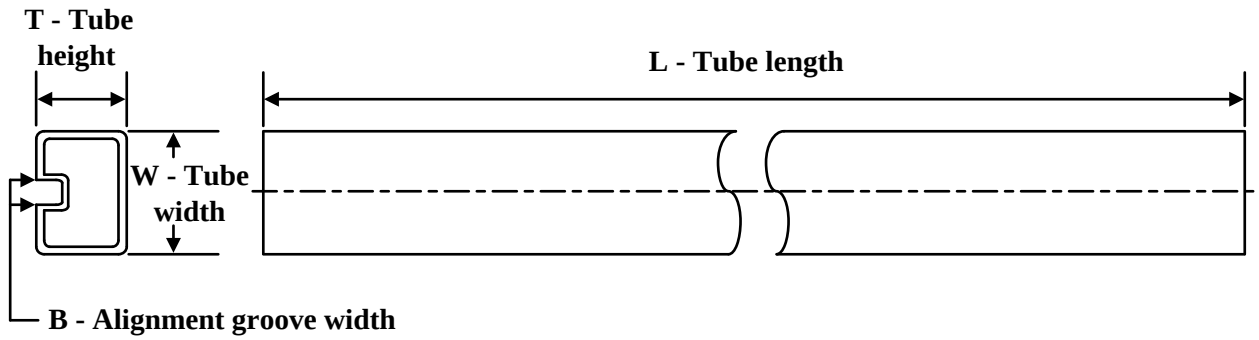
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM79L05ACMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM79L05ACTL/NOPB	DSBGA	YZR	6	250	208.0	191.0	35.0
LM79L05ACTLX/NOPB	DSBGA	YZR	6	3000	208.0	191.0	35.0
LM79L12ACMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM79L15ACMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0

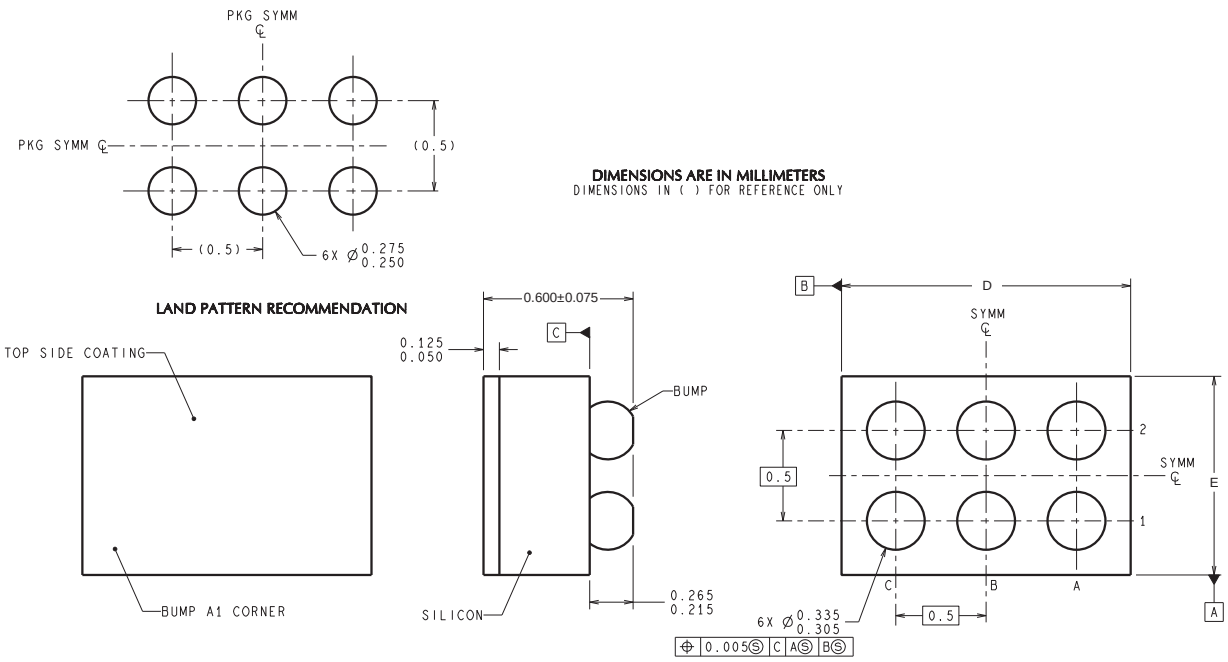
TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
LM79L05ACM/NOPB	D	SOIC	8	95	495	8	4064	3.05
LM79L05ACM/NOPB.B	D	SOIC	8	95	495	8	4064	3.05
LM79L12ACM/NOPB	D	SOIC	8	95	495	8	4064	3.05
LM79L12ACM/NOPB.B	D	SOIC	8	95	495	8	4064	3.05
LM79L15ACM/NOPB	D	SOIC	8	95	495	8	4064	3.05
LM79L15ACM/NOPB.B	D	SOIC	8	95	495	8	4064	3.05

YZR0006



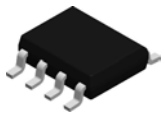
TLA06XXX (Rev C)

D: Max = 1.845 mm, Min =1.784 mm

E: Max = 1.057 mm, Min =0.996 mm

4215044/A 12/12

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
B. This drawing is subject to change without notice.

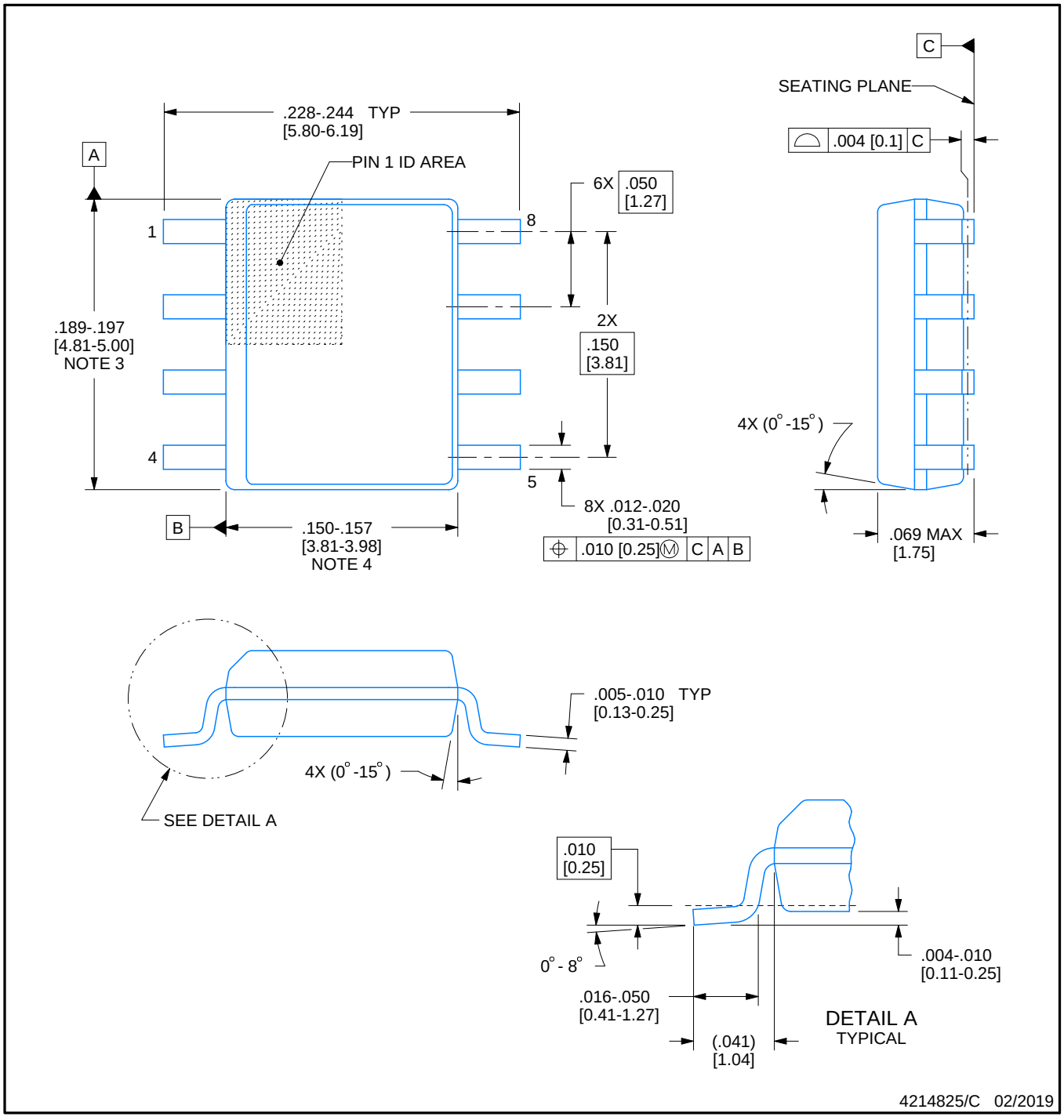


PACKAGE OUTLINE

D0008A

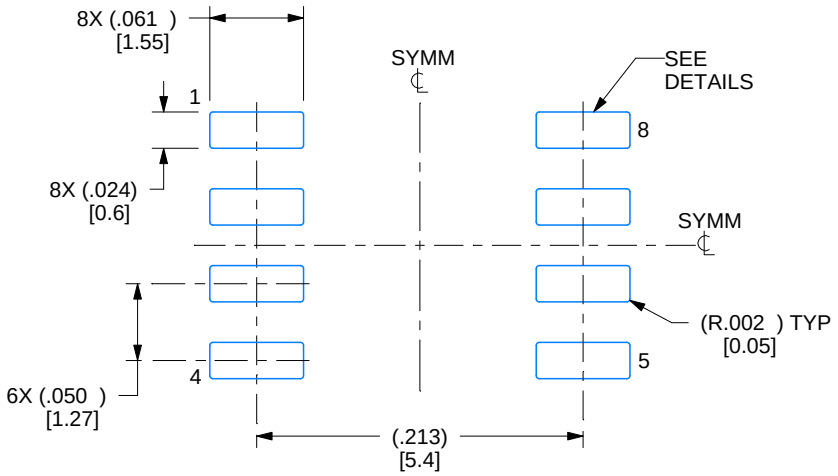
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

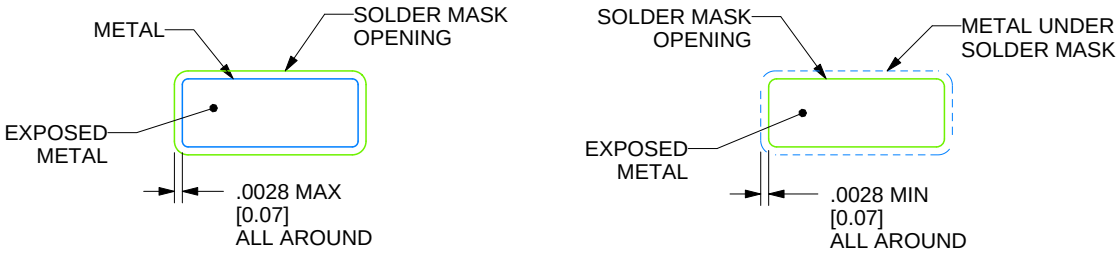


NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

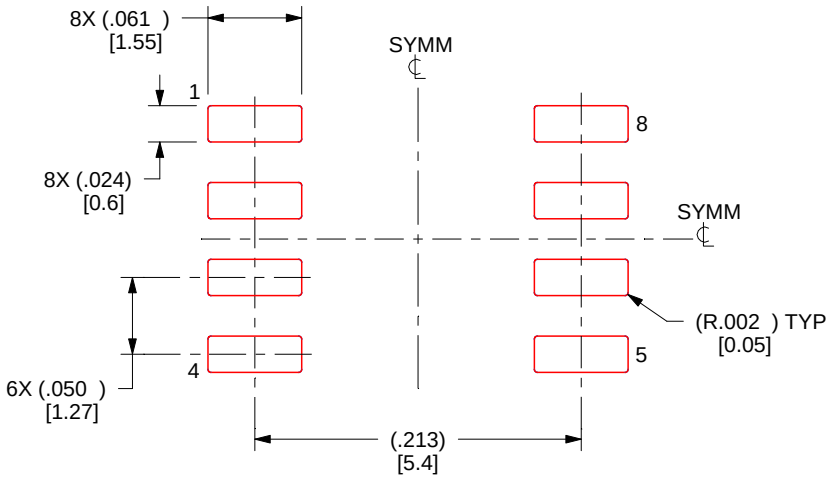
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

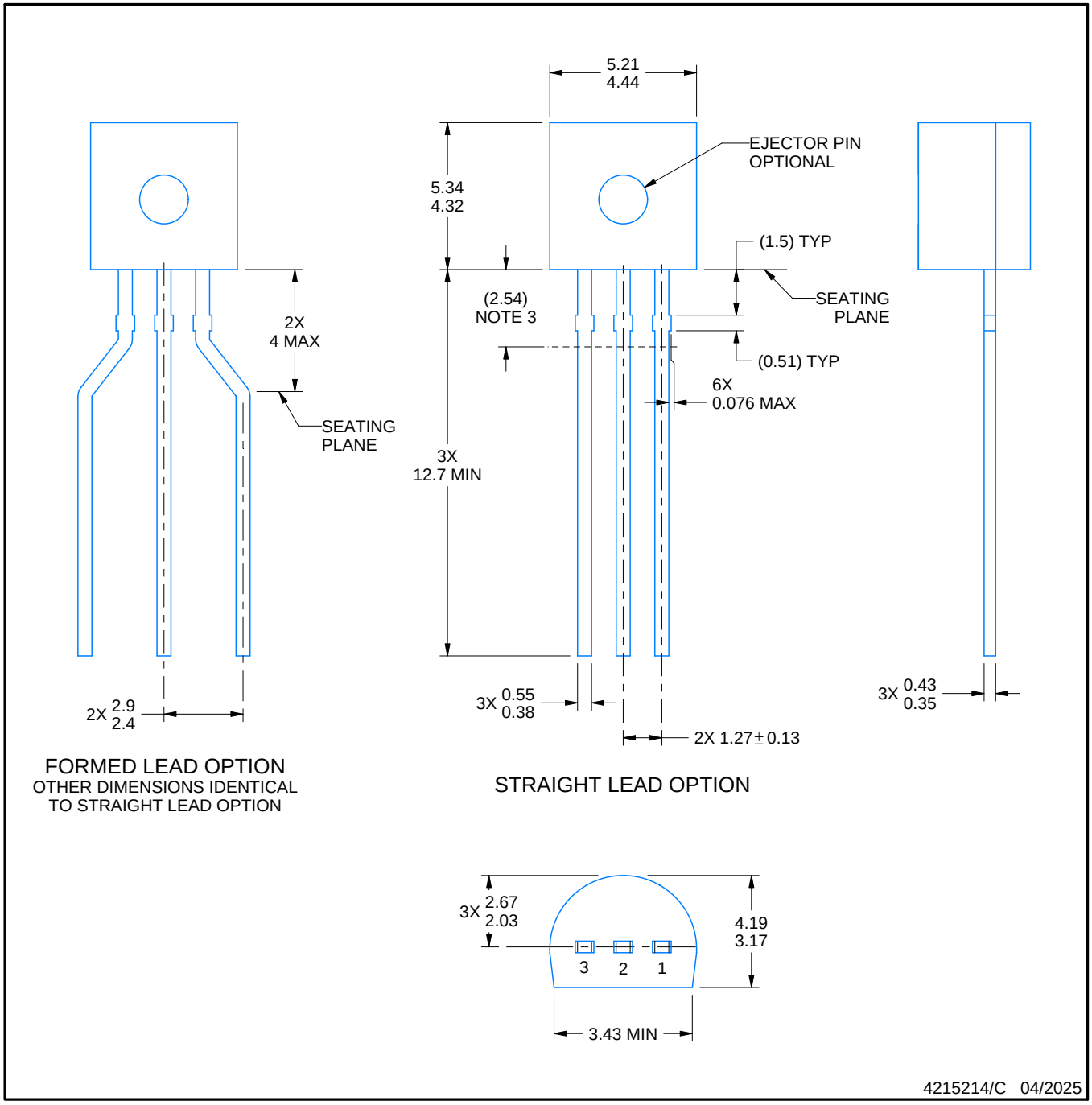
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

LP0003A

PACKAGE OUTLINE

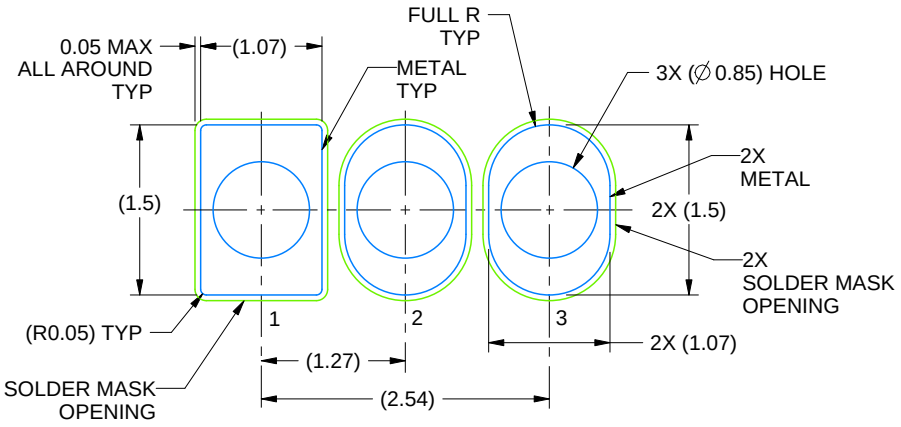
TO-92 - 5.34 mm max height

TO-92

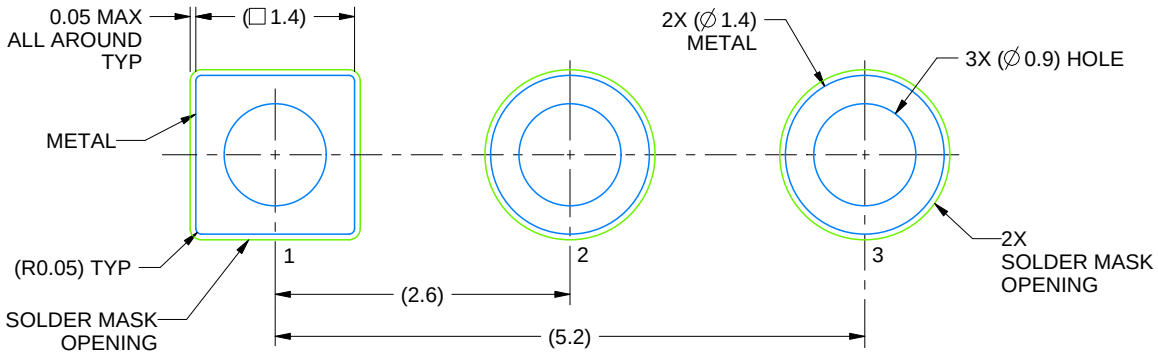


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Lead dimensions are not controlled within this area.
4. Reference JEDEC TO-226, variation AA.
5. Shipping method:
   a. Straight lead option available in bulk pack only.
   b. Formed lead option available in tape and reel or ammo pack.
   c. Specific products can be offered in limited combinations of shipping medium and lead options.
   d. Consult product folder for more information on available options.



LAND PATTERN EXAMPLE
STRAIGHT LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X



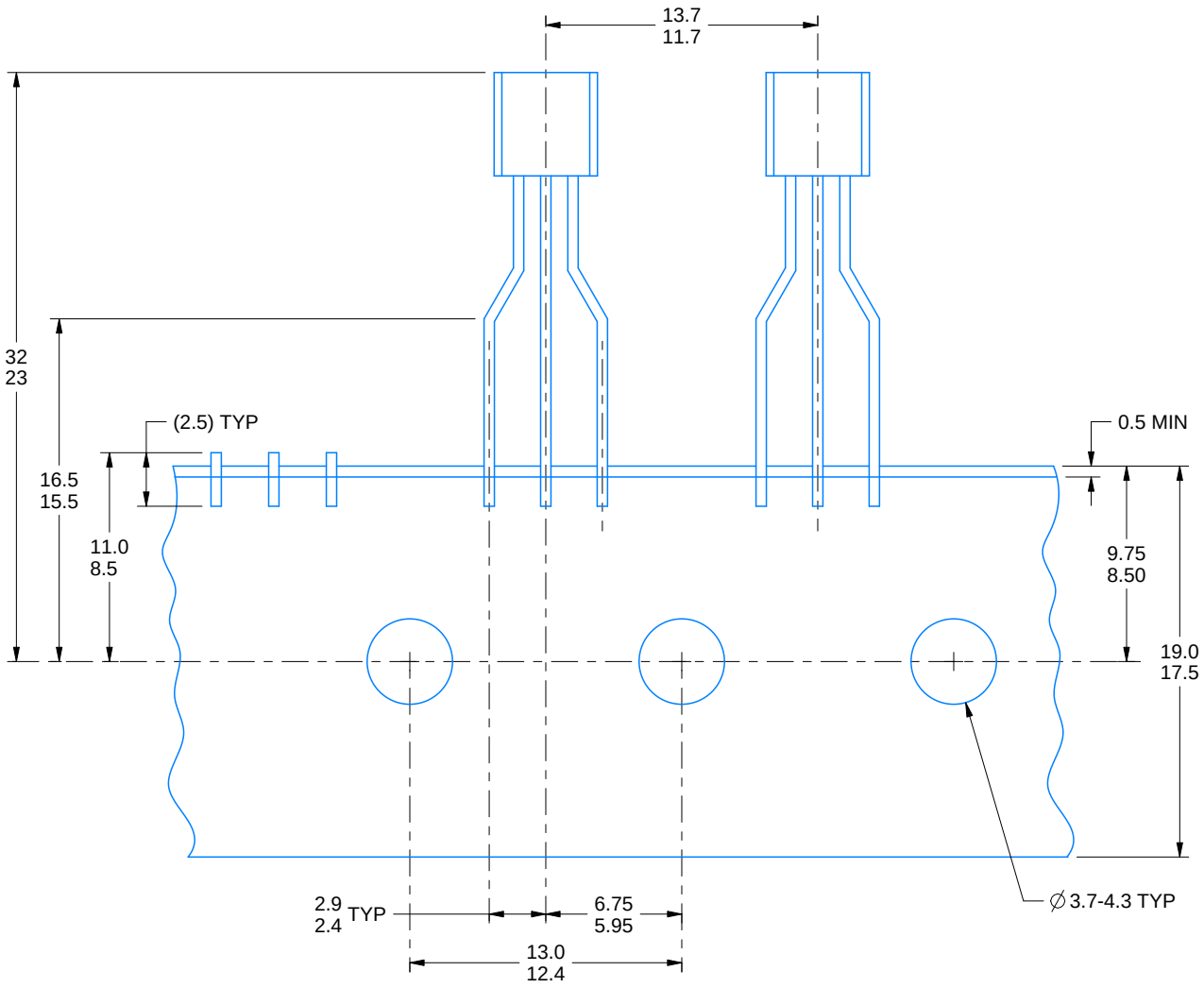
LAND PATTERN EXAMPLE
FORMED LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X

4215214/C 04/2025

LP0003A

TO-92 - 5.34 mm max height

TO-92



FOR FORMED LEAD OPTION PACKAGE

4215214/C 04/2025

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